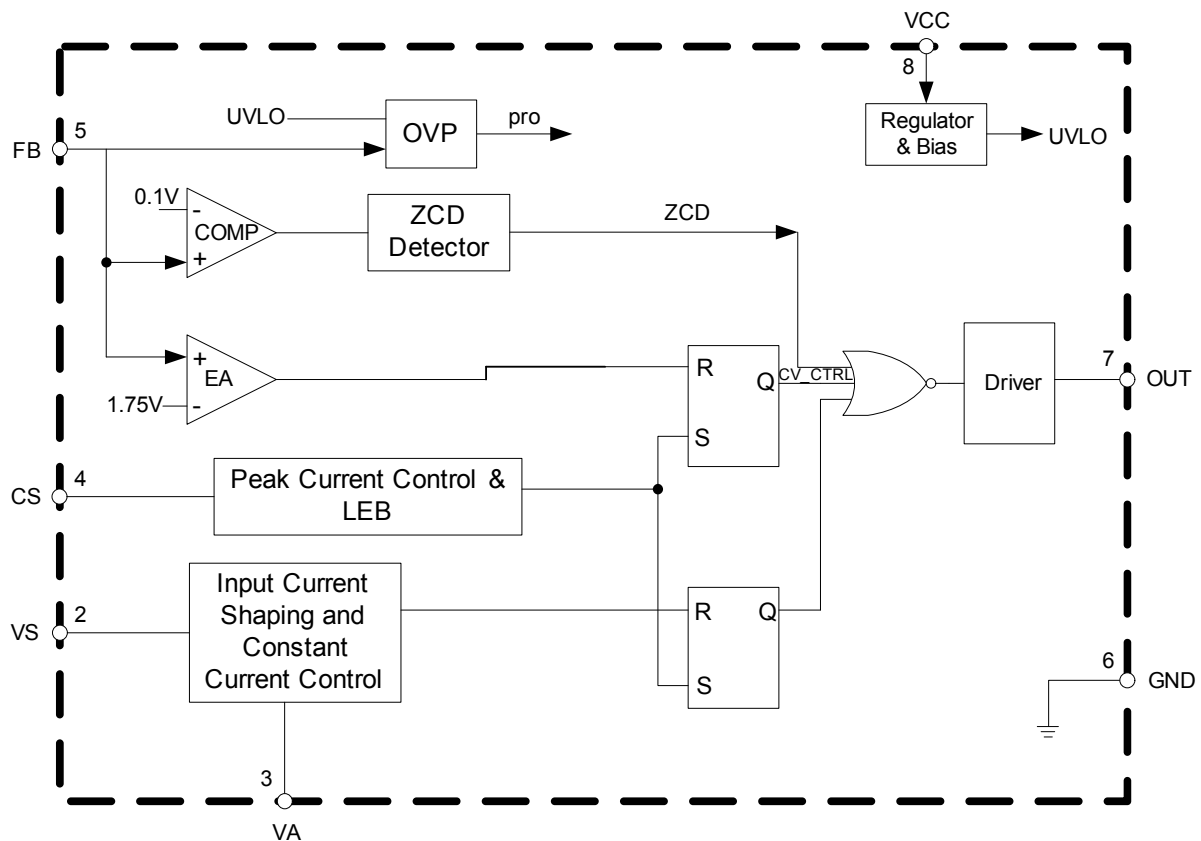


Pin Descriptions

Pin Number	Pin Name	Function
1	NC	No connection
2	VS	Detects the negative terminal voltage of output.
3	VA	Detects the average value of the negative terminal voltage of output.
4	CS	Primary current sensing
5	FB	The feedback voltage sensing from the auxiliary winding
6	GND	Ground
7	OUT	Gate driver output
8	VCC	Supply voltage of gate driver and control circuits of the IC

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified. Note 4)

Symbol	Parameter	Rating	Unit
V _{CC}	Power Supply Voltage	-0.3 to 40	V
I _{OUT}	Driver Output Current	300	mA
V _{VS} , V _{VA} , V _{CS}	Voltage at VS, VA, CS to GND	-0.3 to 7	V
V _{FB}	FB Input Voltage	-40 to 10	V
T _J	Operating Junction Temperature	+150	°C
T _{STG}	Storage Temperature	-65 to +150	°C
T _{LEAD}	Lead Temperature (Soldering, 10 sec)	+300	°C
P _D	Power Dissipation (T _A = +50°C)	0.65	W
θ _{JA}	Thermal Resistance (Junction to Ambient)	190	°C/W
—	ESD (Human Body Model)	3000	V
—	ESD (Machine Model)	200	V

Note 4: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Recommended Operating Conditions

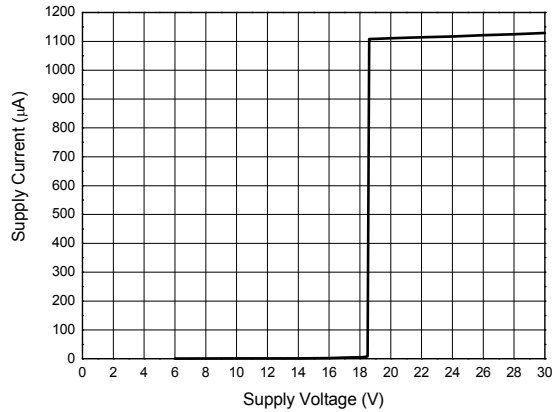
Symbol	Parameter	Min	Max	Unit
V _{CC}	Power Supply Voltage	12	21	V
T _A	Ambient Temperature	-40	+105	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

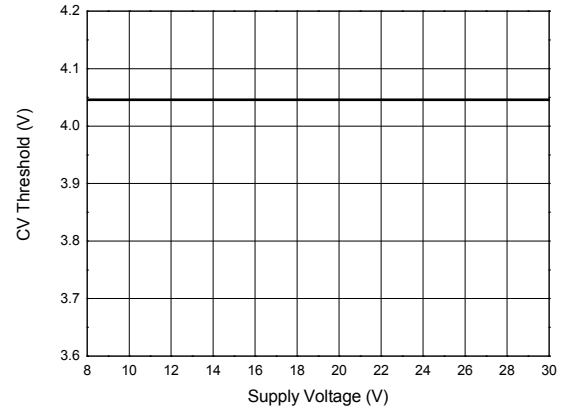
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
UVLO Section						
V _{TH} (ST)	Start-up Threshold	–	18	19	20	V
V _{OPR} (Min)	Minimum Operating Voltage	After turn on	7	8	9	V
V _{CC_OVP}	VCC OVP Voltage	–	28	32	36	V
Standby Current Section						
I _{ST}	Start-up Current	V _{CC} = V _{TH} (ST)-0.5V, Before start up	–	–	20	μA
I _{CC} (OPR)	Operating Current	Static	–	1000	1300	μA
Drive Output Section						
V _{OH}	Output High Level Voltage	I _{GD_SOURCE} = 20mA V _{CC} = 12V	10	–	–	V
V _{OL}	Output Low Level Voltage	I _{GD_SINK} = 20mA V _{CC} = 12V	–	–	1	V
t _R	Output Voltage Rise Time	C _L = 1nF	100	140	190	ns
t _F	Output Voltage Fall Time	C _L = 1nF	30	60	90	ns
V _{O_CLAMP}	Output Clamp Voltage	I _{GD_SOURCE} = 5mA V _{CC} = 20V	12	13.5	15	V
V _{UVLO}	UVLO Saturation Voltage	V _{CC} = 0 to V _{CC_ON} I _{SINK} = 10mA	–	–	1.1	V
Current Sense Section						
t _{ON} (Min)	Minimum On Time	–	500	1000	1500	ns
V _{SOCP}	Short Circuit Protection Voltage	–	3	4	–	V
Feedback Input Section						
I _{FB}	FB Pin Input Leakage Current	V _{FB} = 4V	–	2	8	μA
V _{FB} (CV)	CV Threshold	–	3.8	4.0	4.2	V
V _{FB} (OVP)	Over Voltage Protection	–	4.5	6	7.5	V
VS Input Section						
V _{VS} /V _{VA} (Max)	Maximum Ratio	V _{VS} = V _{VA} = 3V	0.8	1	1.2	V
V _{VS} /V _{VA} (Min)	Minimum Ratio	V _{VS} = 0V, V _{VA} = 3V	–	–	0.2	V
Over Temperature Protection Section						
–	Shutdown Temperature	–	–	+170	–	°C
–	Temperature Hysteresis	–	–	+20	–	°C

Performance Characteristics

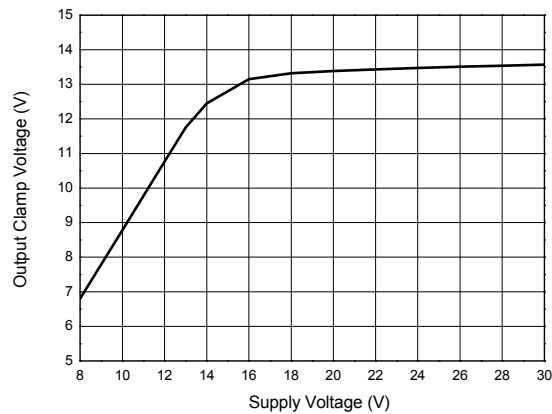
Supply Current vs. Supply Voltage



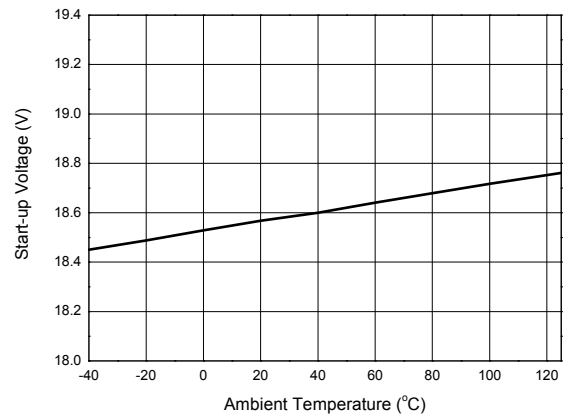
CV Threshold vs. Supply Voltage



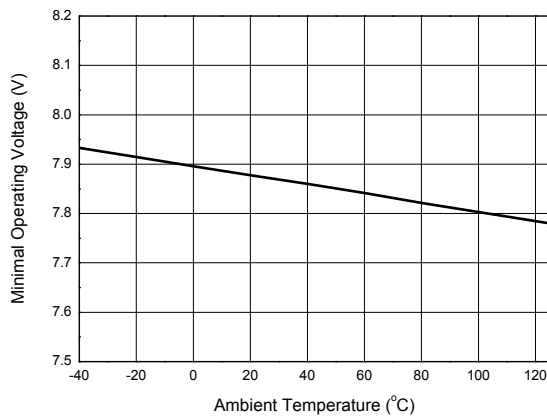
Output Clamp Voltage vs. Supply Voltage



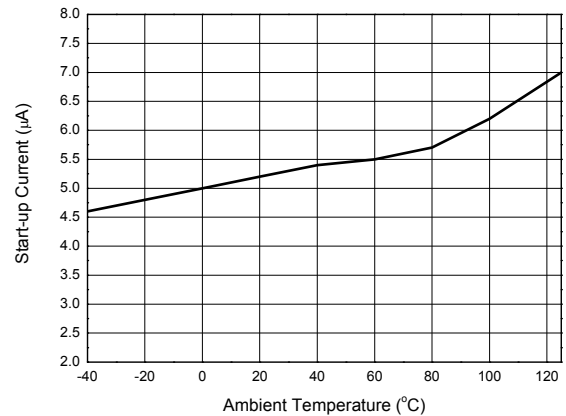
Start-up Voltage vs. Ambient Temperature



Minimal Operating Voltage vs. Ambient Temperature

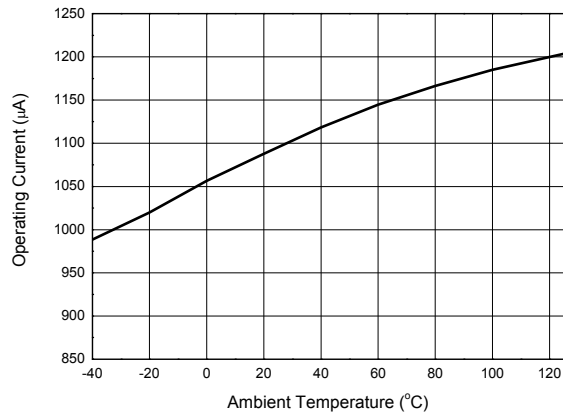


Start-up Current vs. Ambient Temperature

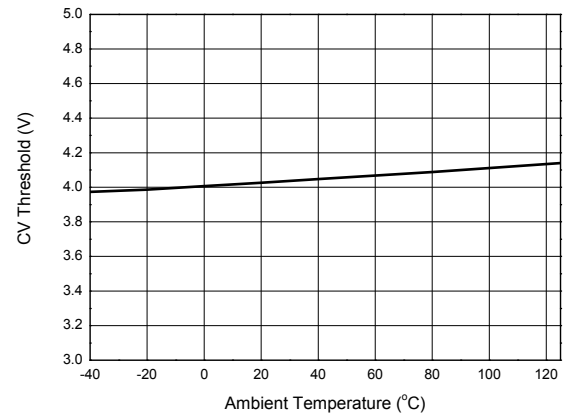


Performance Characteristics (Cont.)

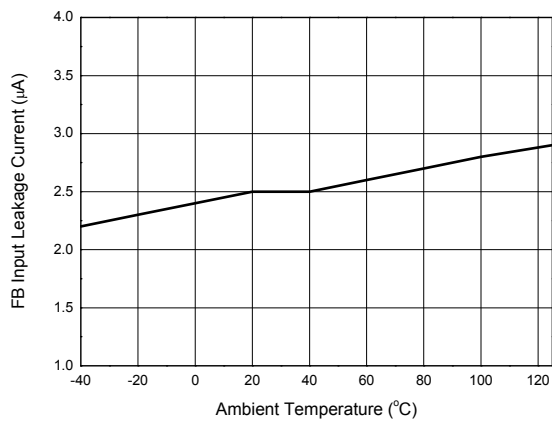
Operating Current vs. Ambient Temperature



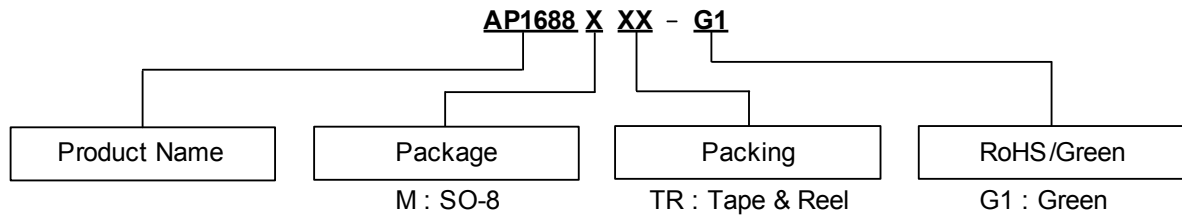
CV Threshold vs. Ambient Temperature



FB Leakage Current vs. Ambient Temperature



Ordering Information

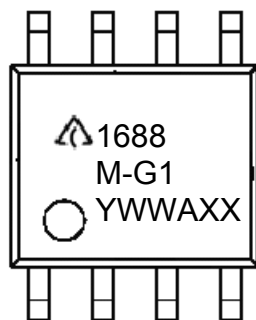


Diodes IC's Pb-free products with "G1" suffix in the part number, are RoHS compliant and green.

Package	Temperature Range	Part Number	Marking ID	Packing
SO-8	-40 to +105°C	AP1688MTR-G1	1688M-G1	4000/13" Tape & Reel

Marking Information

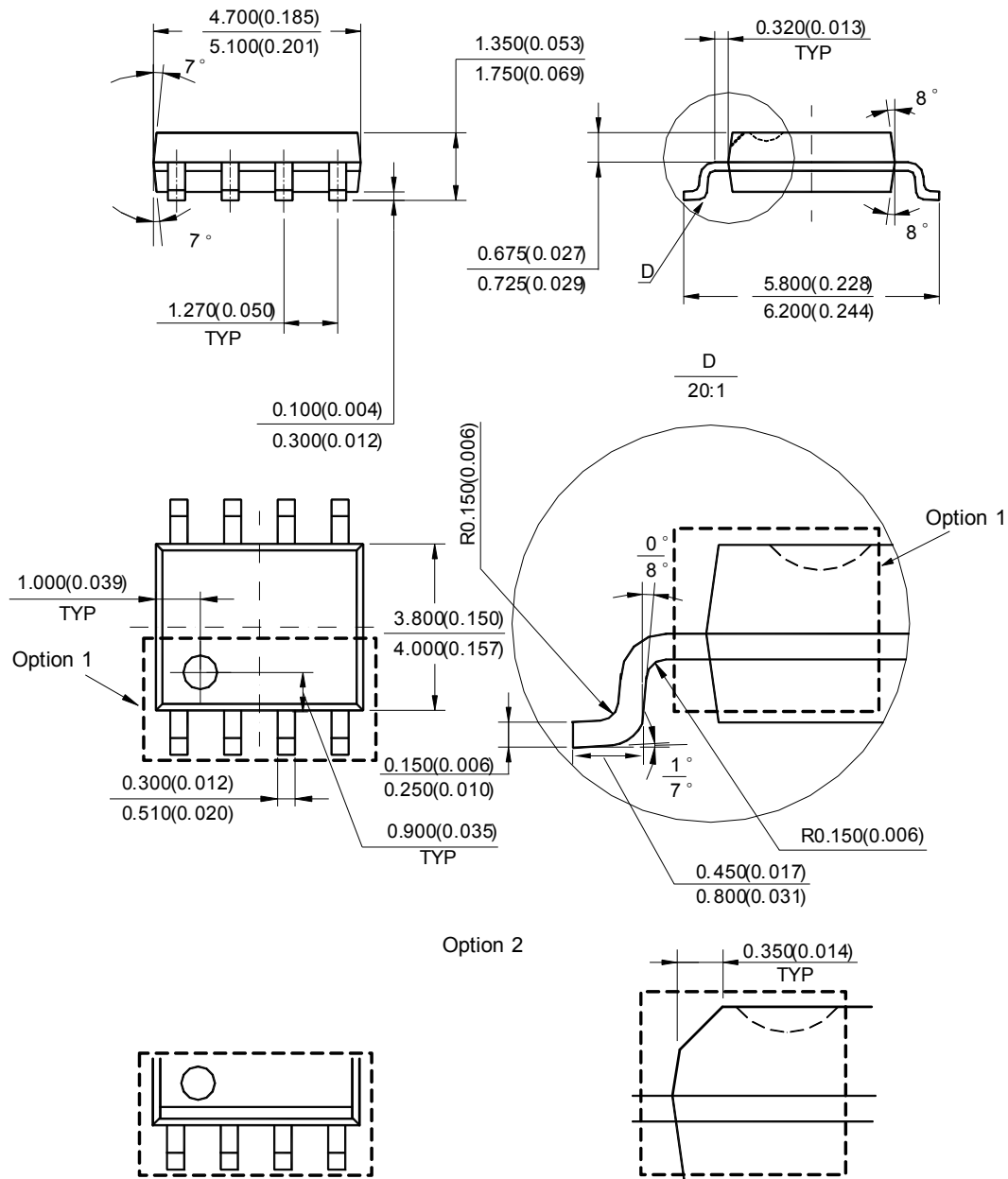
(Top View)



First and Second Lines: Logo and Marking ID
(See Ordering Information)
Third Line: Date Code
Y: Year
WW: Work Week of Molding
A: Assembly House Code
XX: 7th and 8th Digits of Batch No

Package Outline Dimensions (All dimensions in mm(inch).)

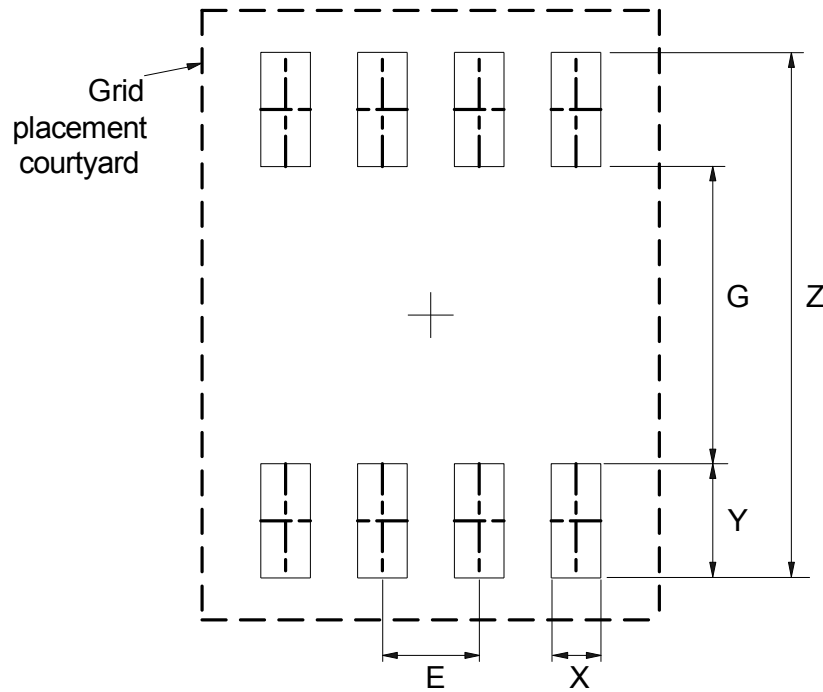
(1) Package Type: SO-8



Note: Eject hole, oriented hole and mold mark is optional.

Suggested Pad Layout

(1) Package Type: SO-8



Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E (mm)/(inch)
Value	6.900/0.272	3.900/0.154	0.650/0.026	1.500/0.059	1.270/0.050

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